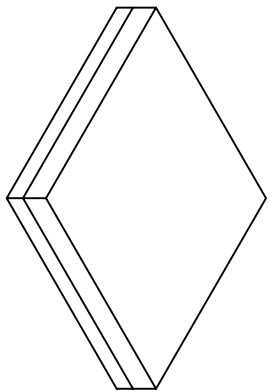


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| REV. | DESCRIPTION | DATE | CHECKED | CONSULTED BY |
|------|----------------------------------|----------|---------|--------------|
| 00 | INITIAL RELEASE PER DCN# C02894 | 01/14/98 | E.B. | JHW |
| 01 | UPDATED TO STANDARDS, DCN C04498 | 08/28/98 | E.B. | HLE |



7. REFERENCE SPECIFICATIONS:
 A. AAWT SPEC #001-0591-2234: PACKING OPERATION PROCEDURE.
 B. AAWT SPEC #001-0519-2062: MARKING.
6. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM Z.
4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BUMPS IS 36.
3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 6 X 6.
2. THE BASIC SOLDER BUMP GRID PITCH IS 0.80.
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- NOTES: UNLESS OTHERWISE SPECIFIED

| UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS | | APPROVALS | | TITLE | |
|--|---------|-----------|----------|-------|---|
| DECIMAL | ANGULAR | DATE | DATE | REV | DESCRIPTION/REV |
| XX ±0.10 | ±1° | 01/06/98 | 01/06/98 | B | PACKAGE OUTLINE - CABGA 36, 6.00mm X 6.00mm, 2 LAYER, 0.80mm PITCH, LAMINATE SUBSTRATE, AAP |
| XXX ±0.05 | | 01/06/98 | 01/06/98 | N/A | |
| MATERIAL | | DATE | DATE | REV | DESCRIPTION/REV |
| N/A | | 01/06/98 | 01/06/98 | N/A | |
| FINISH | | DATE | DATE | REV | DESCRIPTION/REV |
| N/A | | 01/14/98 | 01/14/98 | N/A | |

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SCALE: 8:1 SHEET 1 OF 3